

Vishay Siliconix

N-Channel 40 V (D-S) MOSFET

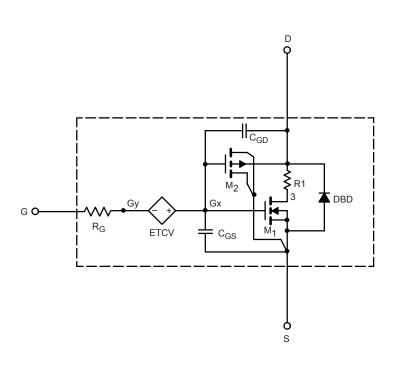
DESCRIPTION

The attached SPICE model describes the typical electrical characteristics of the n-channel vertical DMOS. The subcircuit model is extracted and optimized over the - 55 °C to + 125 °C temperature ranges under the pulsed 0 V to 10 V gate drive. The saturated output impedance is best fit at the gate bias near the threshold voltage. A novel gate-to-drain feedback capacitance network is used to model the gate charge characteristics while avoiding convergence difficulties of the switched C_{gd} model. All model parameter values are optimized to provide a best fit to the measured electrical data and are not intended as an exact physical interpretation of the device.

SUBCIRCUIT MODEL SCHEMATIC

CHARACTERISTICS

- N-Channel Vertical DMOS
- Macro Model (Subcircuit Model)
- Level 3 MOS
- · Apply for both Linear and Switching Application
- Accurate over the 55 °C to + 125 °C Temperature Range
- Model the Gate Charge, Transient, and Diode Reverse Recovery Characteristics



Note

This document is intended as a SPICE modeling guideline and does not constitute a commercial product datasheet. Designers should refer to the appropriate datasheet of the same number for guaranteed specification limits.

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SPECIFICATIONS $T_J = 25 \text{ °C}$, unless otherwise noted					
PARAMETER	SYMBOL	TEST CONDITIONS	SIMULATED DATA	MEASURED DATA	UNIT
Static					
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \ \mu A$	1.4	-	V
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 15 \text{ A}$	0.0031	0.0031	Ω
		$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$	0.0037	0.0035	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, \text{ I}_{D} = 15 \text{ A}$	82	96	S
Diode Forward Voltage ^a	V _{SD}	I _S = 3 A	0.70	0.70	V
Dynamic ^b					
Input Capacitance	C _{iss}	V _{DS} = 20 V, V _{GS} = 0 V, f = 1 MHz	3370	3350	pF
Output Capacitance	C _{oss}		499	490	
Reverse Transfer Capacitance	C _{rss}		204	197	
Total Gate Charge	Qg	$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 10 \text{ V}, \text{ I}_{D} = 10 \text{ A}$	56	59	nC
		$V_{DS} = 20 \text{ V}, \text{ V}_{GS} = 4.5 \text{ V}, \text{ I}_{D} = 10 \text{ A}$	28	28.2	
Gate-Source Charge	Q _{gs}		7.7	7.7	
Gate-Drain Charge	Q _{gd}		9	9	

Notes

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

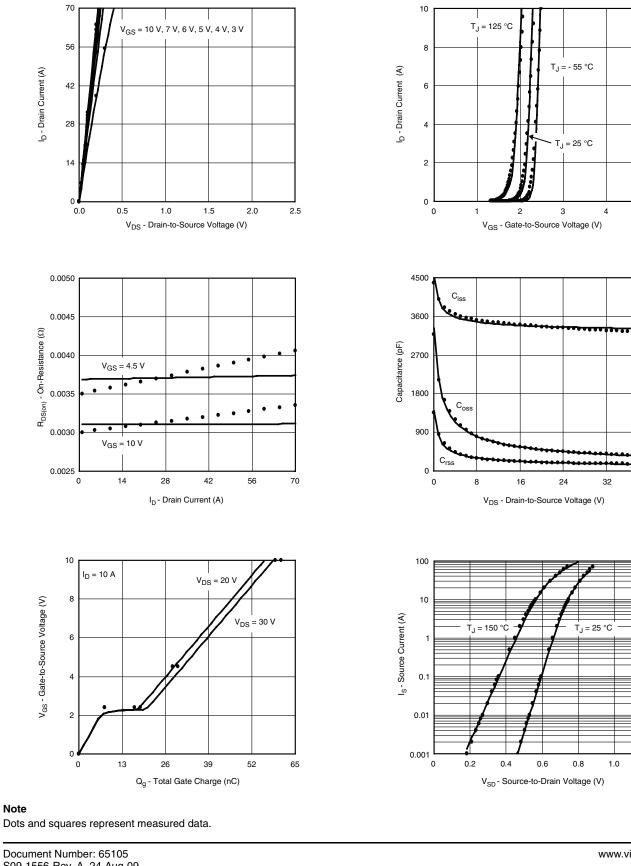


SPICE Device Model SiR416DP

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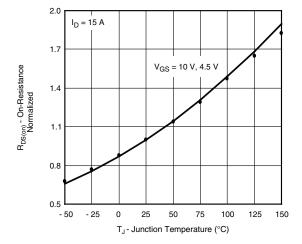
COMPARISON OF MODEL WITH MEASURED DATA T_J = 25 °C, unless otherwise noted

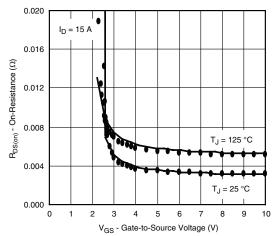
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COMPARISON OF MODEL WITH MEASURED DATA $T_J = 25$ °C, unless otherwise noted







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